

EXHIBIT 6

Applicants: Jan Wendelin Stark, et al.

Serial No.: 10/592,913

Filed: November 13, 2006

Reference 5

Partial Translation

JP Patent Application Disclosure No. 2001-287152 – 16 October 2001

Application No. 2000-108791 – 11 April 2000

Applicant: ACHILLES CORPORATION, Tokyo (JP)

Title: POLISHING SHEET FOR SEMICONDUCTOR WAFER AND
METHOD FOR MANUFACTURING THE SAME

[Descriptive part of the specification]

.....

[0014]

Examples of the polishing material in the form of fine powder used in the polishing sheet for semiconductor wafers provided by the present invention in this case include: silica oxide, silicon oxide, aluminum oxide, zirconium oxide, cerium oxide, titanium oxide, chromium oxide, silicon carbide, boron nitride, glass fibers, alumina fibers, alumina-silica fibers, silica fibers, boron fibers, carbide fibers, and silicon carbide. Among these, silica oxide and cerium oxide are preferred.

.....

ABRASIVE SHEET FOR SEMICONDUCTOR WAFER AND MANUFACTURING METHOD THEREFOR

Publication number: JP2001287152 (A)

Publication date: 2001-10-16

Inventor(s): TOTSUNE SHIGERU; KAWANAMI YOSHIHIRO +

Applicant(s): ACHILLES CORP +

Classification:

- international: **B24B37/00; C08J5/14; C08J9/40; C08K3/00; C08L75/04; C09K3/14; H01L21/304; B24B37/00; C08J5/14; C08J9/00; C08K3/00; C08L75/00; C09K3/14; H01L21/02; (IPC1-7): B24B37/00; C08J5/14; C08J9/40; C08K3/00; C08L75/04; C09K3/14; H01L21/304**

- European:

Application number: JP20000108791 20000411

Priority number(s): JP20000108791 20000411

Abstract of JP 2001287152 (A)

PROBLEM TO BE SOLVED: To provide an abrasive sheet for semiconductor wafers with flatly and closely processed surface, with abrasive uniformly added, and with low elasticity, thereby capable of strongly pressed polishing, without damaging a semiconductor substrate in polishing. **SOLUTION:** This abrasive sheet for semiconductor wafers manufactured by impregnating and attaching urethane based emulsion resin liquid with fine- powder abrasive uniformly dispersed into soft polyurethane foam or semi-hard polyurethane foam, especially its surface, and by compression molding into a resin form.

Data supplied from the **espacenet** database — Worldwide